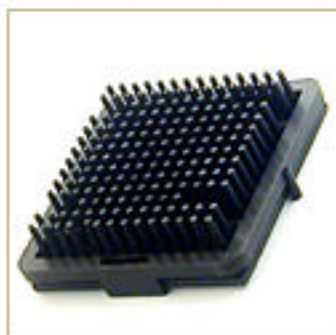




BGA Snap-on Heatsinks

EMULATION TECHNOLOGY, INC.

World Leader in Adapters, Clips, and Test Accessories



Standard BGA product provided as:

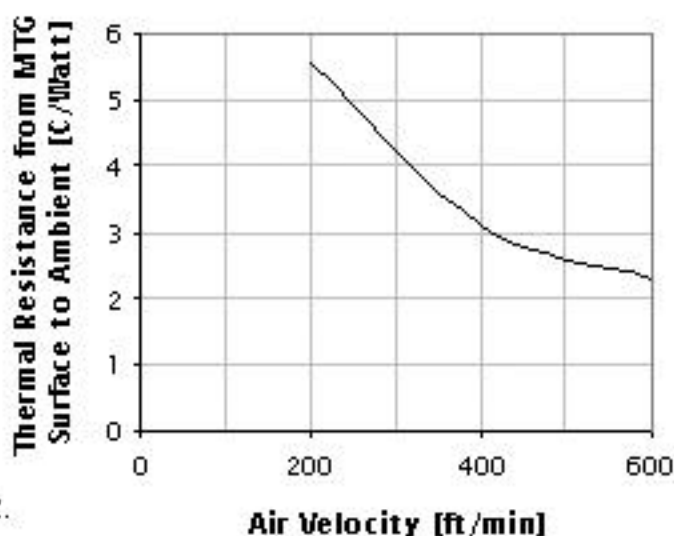
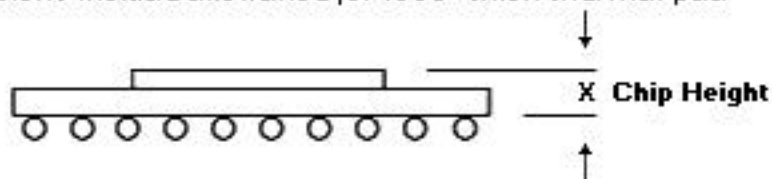
- Black anodized
- Pre-assembled as shown
- Customs available upon request

Other BGA products available:

- Rework Stencils
- Reballing Preforms
- Sockets
- Ultra-mini Pogo Pins

ET Part Number	Part Marking	Chip Pkg. Size (sq)	Heatsink Height	Fits Chip Height [x]
H-4503-07-9016-05-A	HS2129DCAB	45 mm	0.3 in (7.62 mm)	1.88 (+/- 0.26) mm
H-4503-08-9016-05-A	HS2093DCAB	45 mm	0.3 in (7.62 mm)	1.38 (+/- 0.26) mm

* Max dimensions include allowance for .005" thick thermal pad



— HS2129DCAB HS2093DCAB

EMULATION TECHNOLOGY, INC.
2344 WALSH AVE.
BLDG. F
SANTA CLARA, CA 95051
1-800-ADAPTER (232-7837)
www.1800ADAPTER.com